



*Competence in Silicon*

# The numerous configurations of „interstitial boron“ and their involvement in ARP of LGADs

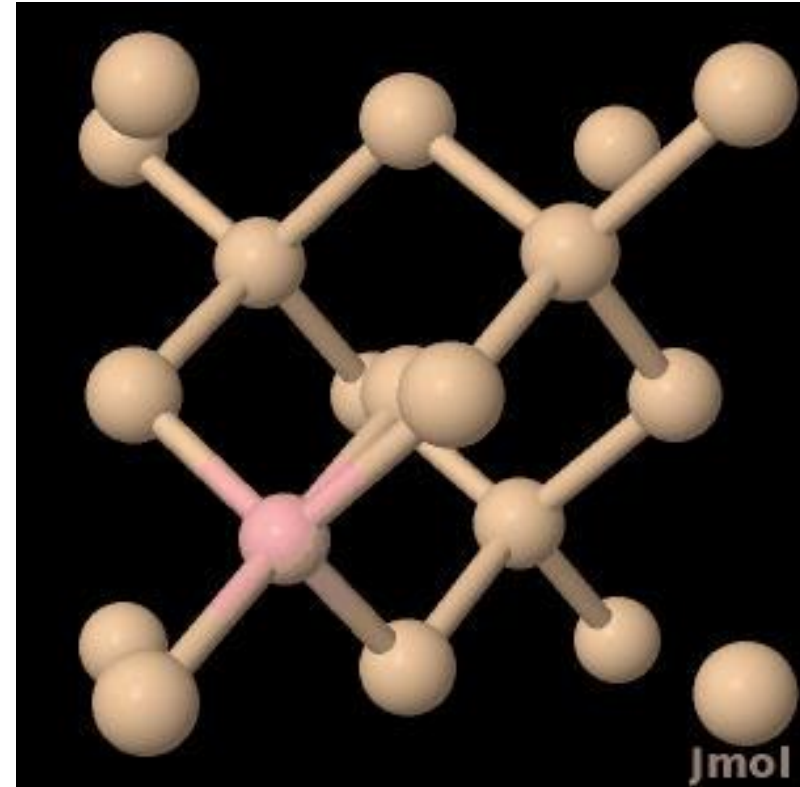
30.11.2023

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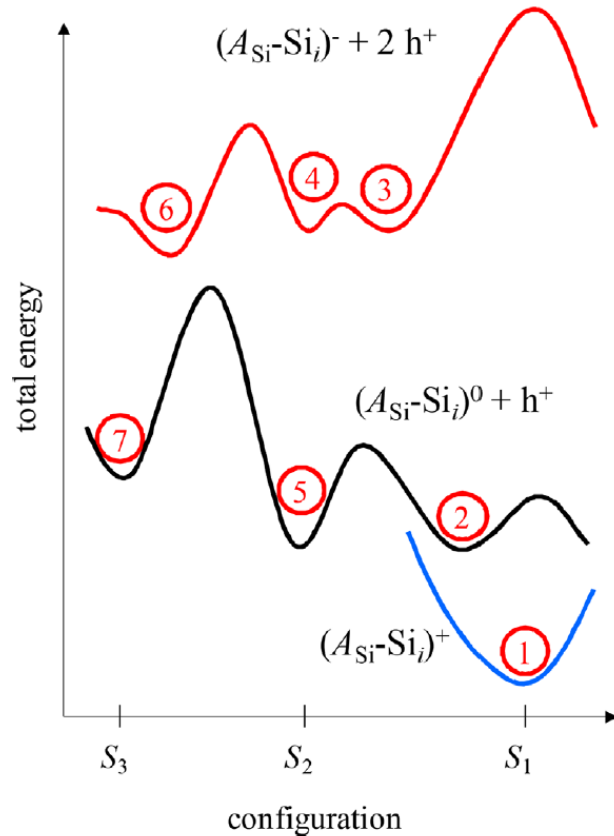
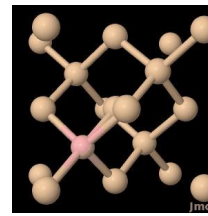
## Existing $A_{Si}$ - $Si_i$ -defect model

# $A_{Si}$ - $Si_i$ defect model

- $A_{Si}$ : acceptor atom is close to its substitutional position
- Silicon interstitial is moving around (tetrahedral, hexagonal and split interstitial position assumed so far)
- Model and experimental evidence recently reviewed [1]

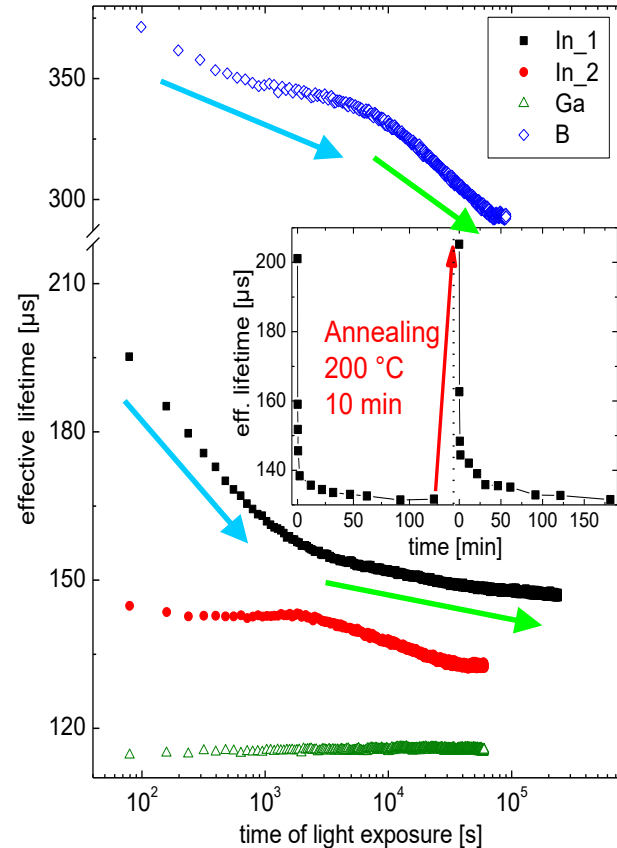
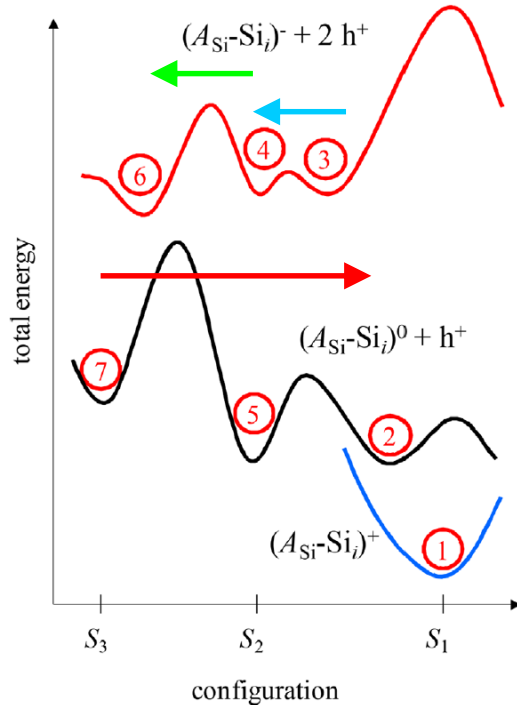


# $A_{Si}-Si_i$ defect model



- Configuration coordinate total (electronic + elastic) energy diagram [1] deduced from simulation results of the silicon interstitial [2]
- Three charge states (+, 0, -) and three configurations ( $S_1$ ,  $S_2$  and  $S_3$ ) of  $A_{Si}-Si_i$  exist within the model
- Energy barriers between configurations (e.g.  $E_{34}$ ,  $E_{46}$ )
- Negative charge state:  $S_3$  energetically favored
- Neutral charge state:  $S_2$  and  $S_1$  energetically favored

# Explanation of LID by $A_{Si}-Si_i$ defect model



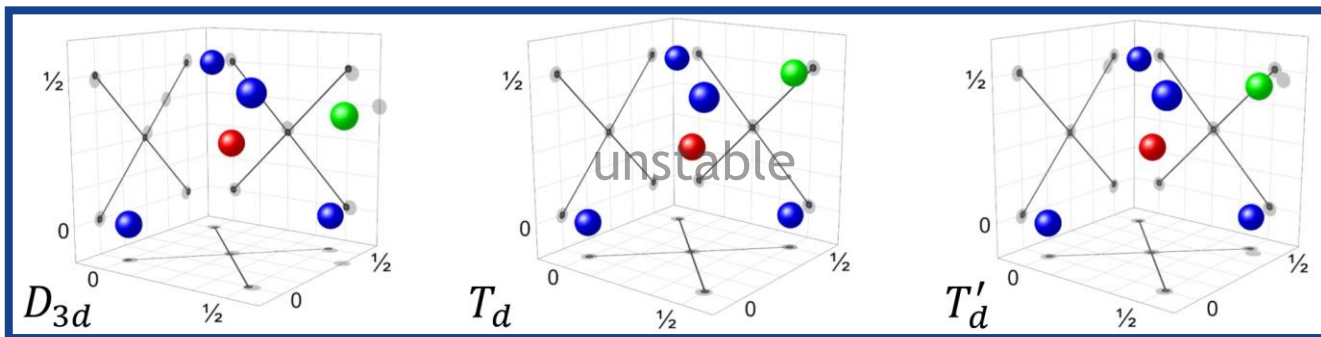
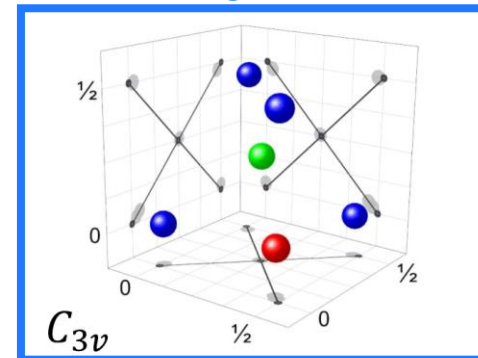
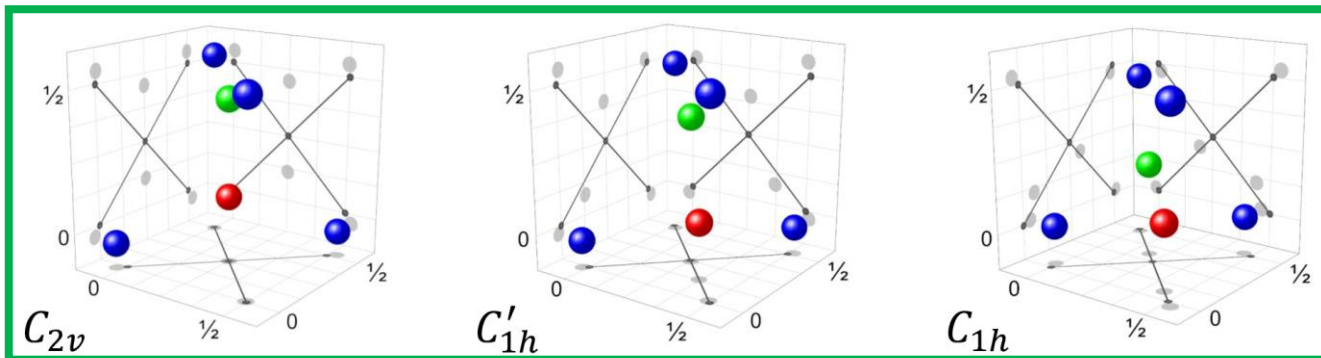
- **LID:** light-induced degradation in silicon solar cells [1]
- **Transition 1 to 3:** defect captures electrons under illumination
- **Transition 3 to 4:** thermally stimulated, fast component of LID (FRC)
- **Transition 4 to 6:** thermally stimulated, slow component of LID (SRC)
- **Transition 7 to 1:** thermally stimulated, recovery of defect, without illumination

# Configurations of “interstitial boron” obtained by DFT calculations

# DFT calculation of stable defect configurations

$B_i Si_i V$

$B_{Si} Si_i$



$B_i$

- Si Bulk
- Si defect
- B defect
- projection of atoms to {100} planes
- projection of lattice sites to {100} planes

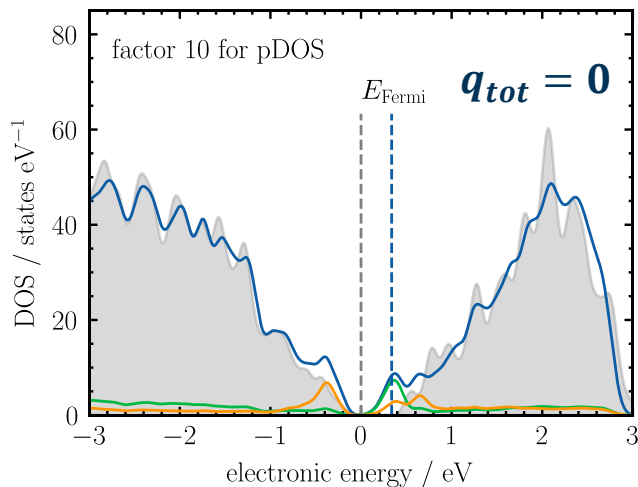
● Six different stable configurations found



# DFT calculation of density of states (DOS)

## $B_iSi_iV$ defect ( $C_{1h}$ )

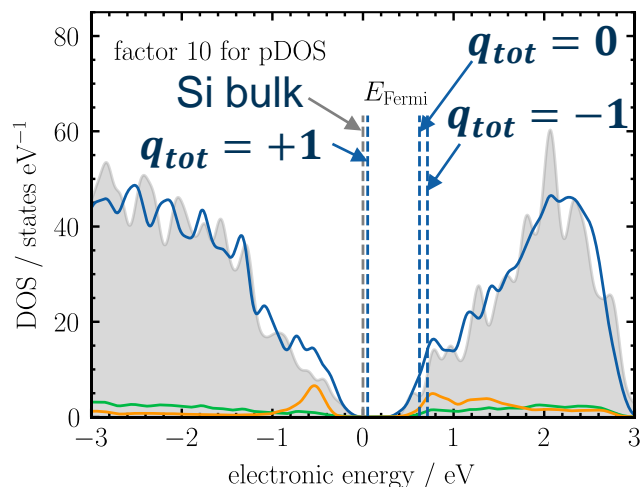
clean Si  $B_{Si}$  pDOS  
total DOS  $Si_i$  pDOS



→ Deep donor

## $B_{Si}Si_i$ defect ( $C_{3v}$ )

clean Si  $B_{Si}$  pDOS  
total DOS  $Si_i$  pDOS

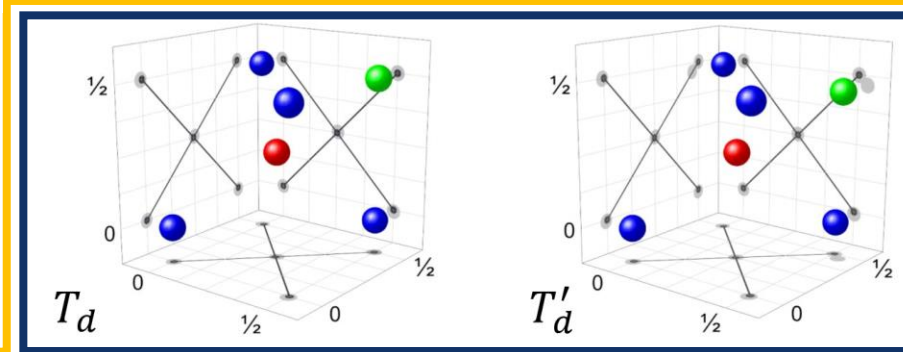
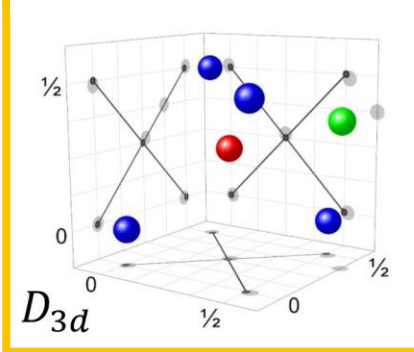
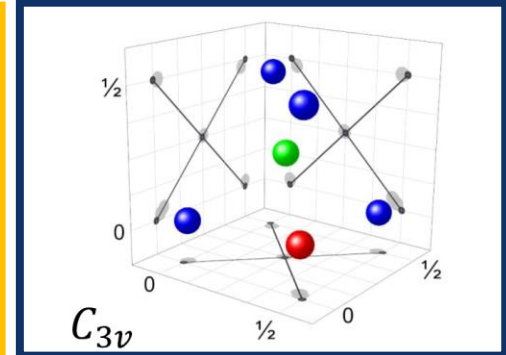
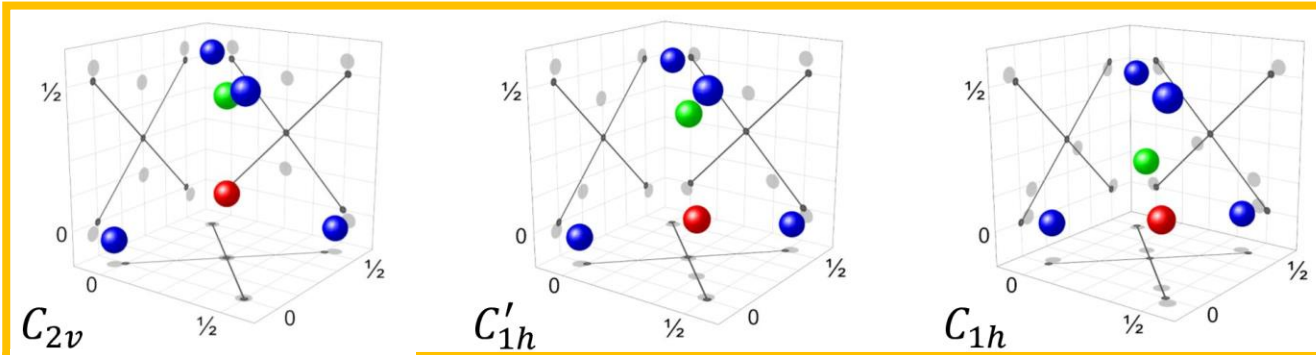


→ Shallow donor

- $B_{Si}Si_i$  defect in  $C_{3v}$  configuration is shallow donor

# Calculated electronic defect states

deep



shallow

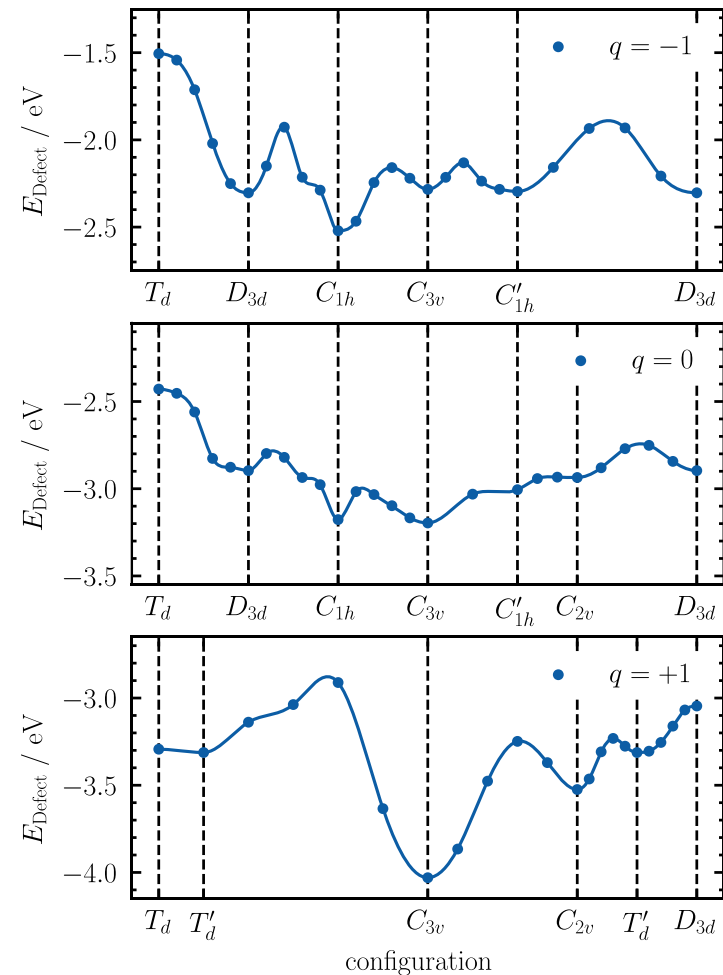
- Si Bulk
- Si defect
- B defect
- projection of atoms to {100} planes
- projection of lattice sites to {100} planes

● 4 deep and 3 shallow centers found

# Defect energy landscape

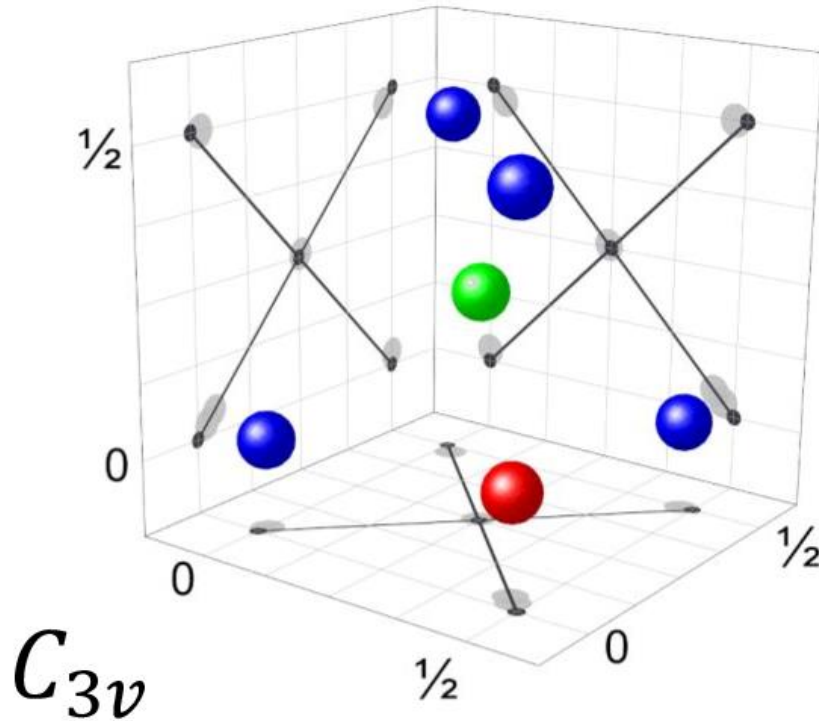
# Calculated defect energy landscape

- Calculation of all Minimal Energy Paths (NEB method) between defect configurations for each charge state
- Ground state in positive charge state (p-type silicon) is  $C_{3v}$  configuration
- From DFT calculations: no energetical reason for the substitutional boron to follow the Watkins replacement reaction!



# Explanation of ARP in LGADs by the $B_{Si}$ - $Si_i$ -defect mode

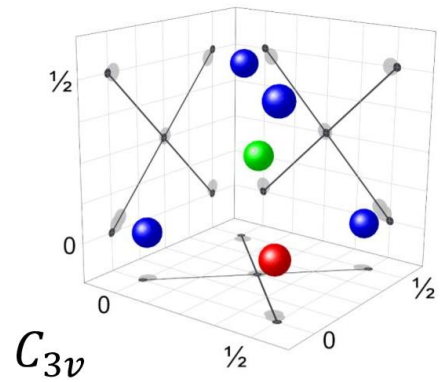
# Explanation of ARP in LGADs by $B_{Si}-Si_i$ -defect mode



- Irradiation removes silicon atoms from lattice positions
- At low temperatures ( $\sim 20K$ ) the removed silicon atom moves due to the energy gained by the collision event and is eventually captured by substitutional boron. [1]
- At about room temperature the removed silicon atom might additionally diffuse thermally due to its weak mobility. [2]
- Shallow donor mode of the  $B_{Si}-Si_i$ -defect ( $C_{3v}$ ) forms

# Summary

- Comprehensive DFT calculations made for “interstitial boron”
- Six different stable configurations found
- Configuration with lowest energy in p-type silicon is  $C_{3v}$  with boron residing very close to regular lattice position
- $C_{3v}$  configuration is found to be a shallow donor
- Explanation of acceptor removal phenomenon (ARP) in low-gain avalanche detectors (LGAD):
  - Substitutional boron acceptor captures silicon atom, which was removed from a lattice position by irradiation.
  - The resulting defect is a shallow donor.
  - Amplification property of the boron gain layer in LGADs gets lost by irradiation.



# Thank you for your kind attention!

DFG Project SimASiSii:

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**Thanks to RD50 for possibility to present crazy ideas!**



# Back-up

# Possibility for silicon recoils to reach B atoms

- 1 MeV electron irradiation of silicon generates silicon recoils exhibiting kinetic energy
- ~10% of these recoils have more than 80eV
- ~50% of these 10% travel more than 1nm (SRIM)
- For  $10^{16}\text{cm}^{-3}$  boron density every 23th of these left recoils is able to reach a boron atom
- If 10% of the silicon recoils reaching boron to form the  $\text{B}_{\text{Si}}\text{-Si}_i$ -defect, a  $\text{B}_{\text{Si}}\text{-Si}_i$ -defect density of about  $10^{15}\text{cm}^{-3}$  is under typical conditions (electron current and duration) possible.
- => Sufficient to explain EPR signals [1] without assumption of fast defect diffusion [2]

